

描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20~200V，正向电流：3.0A，薄型 SOD-123FL 封装。

Surface Mount Schottky Barrier Rectifier, Reverse Voltage: 20 to 200 V, Forward Current: 3.0A, SOD-123FL thin package.

特征 / Features

低功率损失，高效率，高正向浪涌电流能力，适用于低压、高频转换和极性保护，适用于表面贴装。无卤产品。

Low power loss, high efficiency, High forward surge current capability, For use in low voltage, high frequency inverters and polarity protection applications, For surface mounted applications. Halogen free product.

用途 / Applications

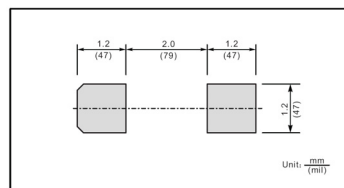
一般用途.

General purpose.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size

**印章代码 / Marking**

见印章说明。See Marking Instructions.


极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		DS32W	DS34W	DS36W	DS38W	DS310W	DS312W	DS315W	DS320W	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F (AV)}	3.0								A
Peak Forward Surge urrent,8.3ms Single Half ine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80				70				A
Typical Junction Capacitance ¹⁾	C _i	250		160						pF
Typical Thermal Resistance ²⁾	R _{θJA}	40								℃/W
Operating Junction Temperature Range	T _j	-55~+125								℃
Storage Temperature Range	T _{stg}	-55~+150								℃

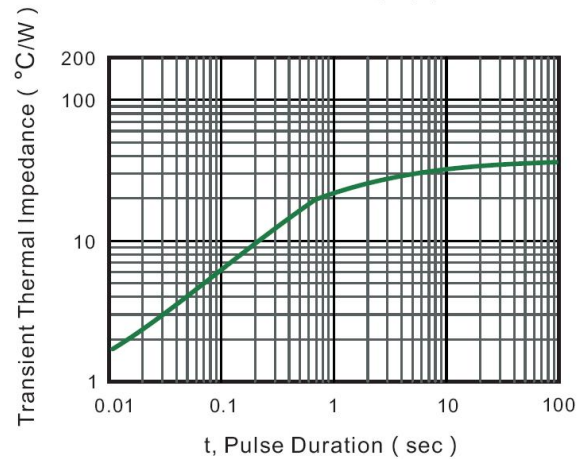
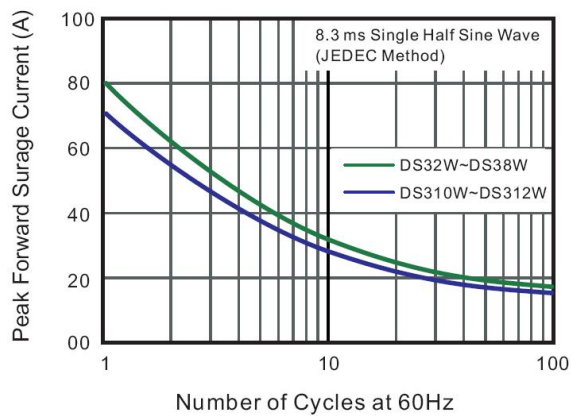
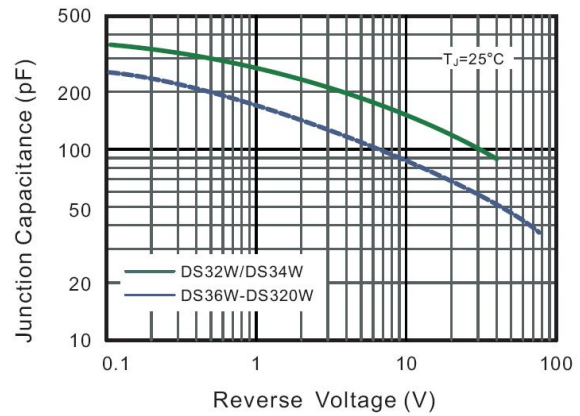
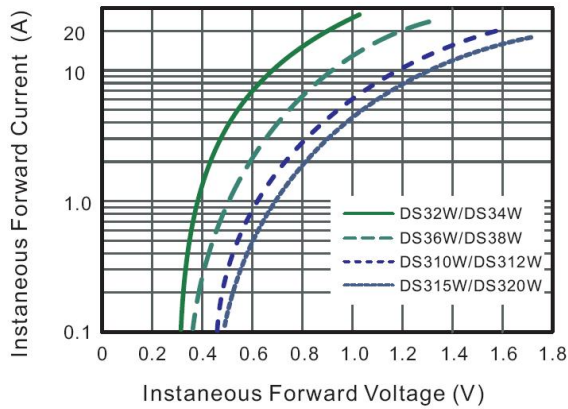
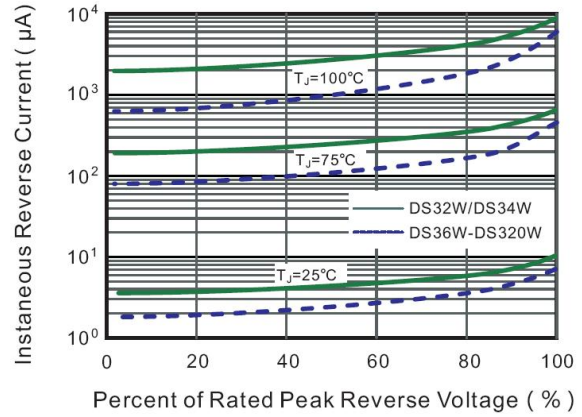
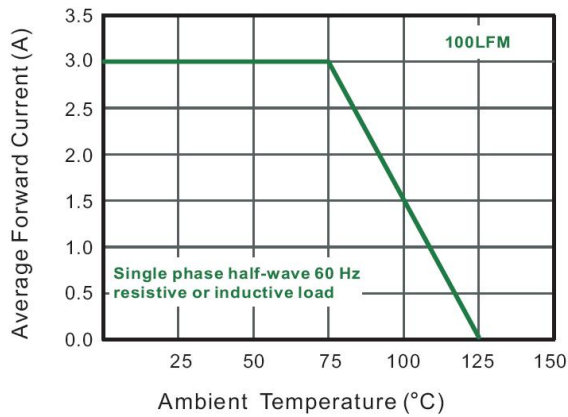
Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
 2) P.C.B. mounted with 0.2 X 0.2" (5 X 5 mm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

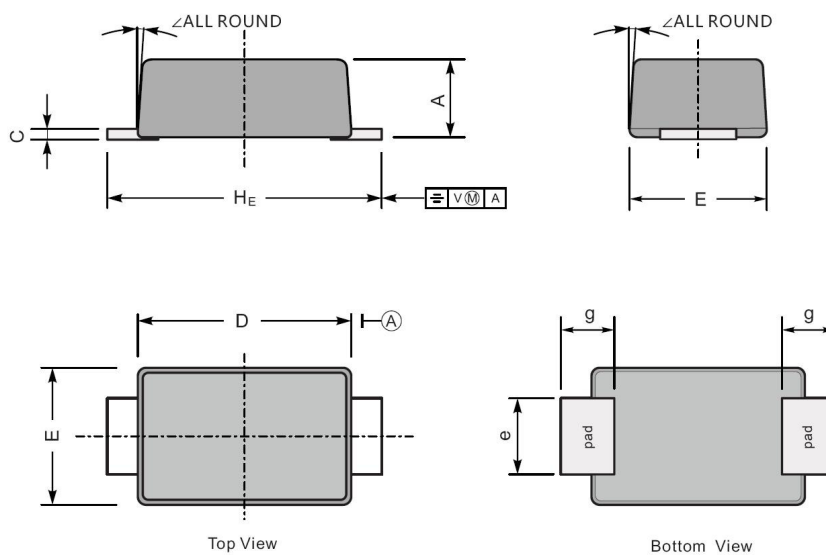
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating								单位 Unit
			DS32W	DS34W	DS36W	DS38W	DS310W	DS312W	DS315W	DS320W	
Max Instantaneous Forward Voltage	V _F	I _F =3.0A	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I _R	T _a =25℃	0.5			0.3					mA
		T _a =100℃	10			5.0					

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SOD-123FL



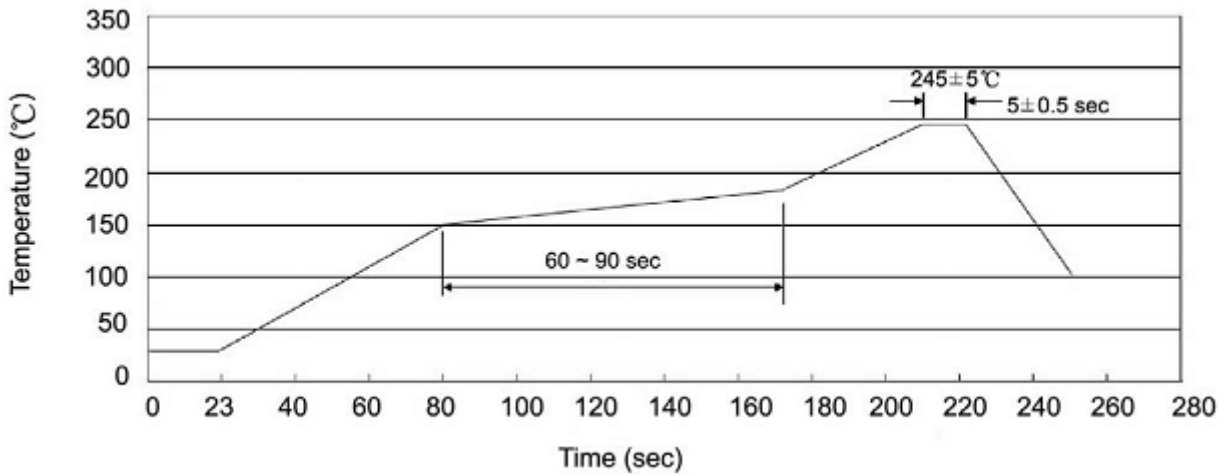
UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

印章说明 / Marking Instructions

Marking

Type number	Marking code
DS32W	S32
DS34W	S34
DS36W	S36
DS38W	S38
DS310W	S310
DS312W	S312
DS315W	S315
DS320W	S320

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



- 说明：

 - 1、预热温度 25 ~ 150℃，时间 60 ~ 90sec;
 - 2、峰值温度 245±5℃，时间持续为 5±0.5sec;
 - 3、焊接制程冷却速度为 2 ~ 10℃/sec.
- Note:

 - 1.Preheating:25~150℃, Time:60~90sec.
 - 2.Peak Temp.:245±5℃, Duration:5±0.5sec.
 3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec.

Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123FL	3000	8	24000	5	120000	7" ×11	185X180X105	550X210X220

使用说明 / Notices